



High Power Inspection System

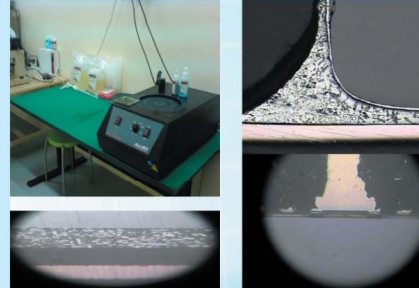


Bench Measurement System

Failure Analysis - Chemical Decapsulation

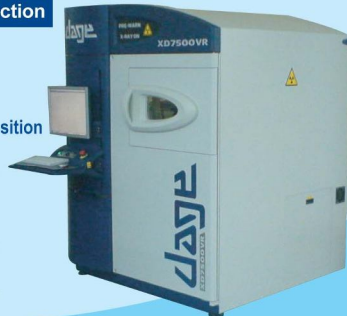
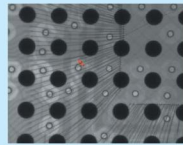


Failure Analysis - Package Grind/Polisher



Failure Analysis - Real time X ray inspection

- Capabilities :
- Energy : 30 to 160KV
 - Oblique angle view
 - 0 to 70deg for any view
 - 360degC around any position



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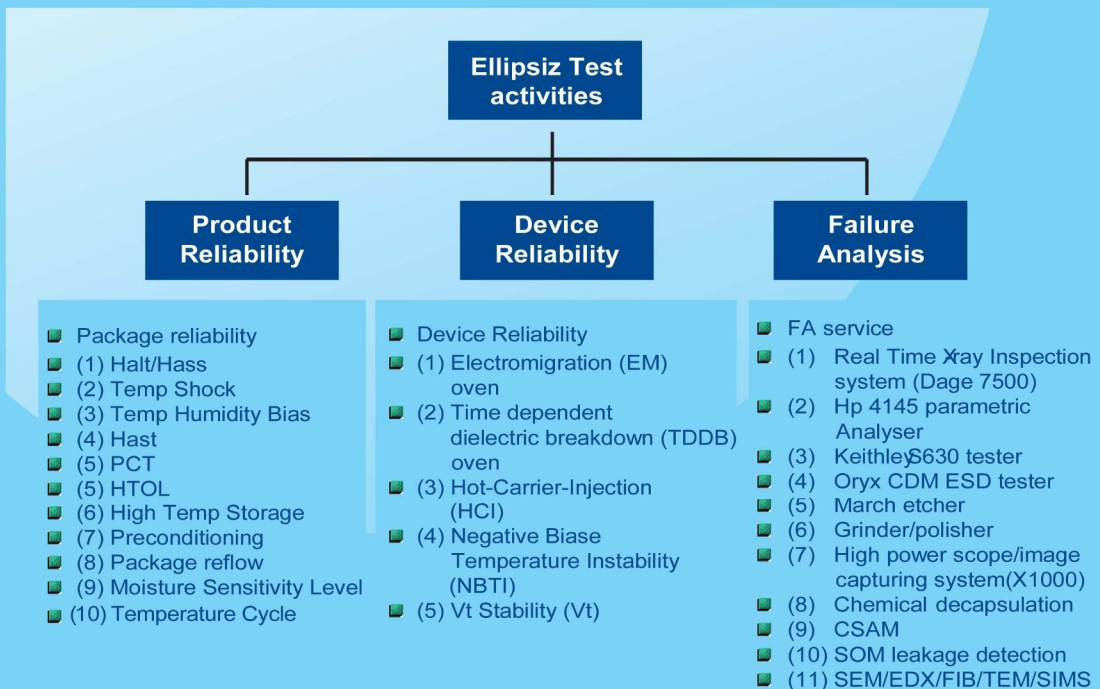
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ellipsiz Ellipsiz TestLab Pte Ltd

We are specialist and provider of failure analysis and reliability test services.
We have a broad base of customers and we provide the followings services:

- Failure Analysis Service
- Product Reliability Service
- Device Reliability Service
- Test Structures (Design, Verification and Test)
- Technology Qualification Support for Semiconductor
- Semiconductor Reliability Training and Consultation
- Thermal and Humidity Measurement Service
- Semiconductor Packaging
- ESD Test and Qualification
- Other Test Services Outsource





Product Reliability - Thermal Shock

Capabilities :
 Hot Temp range : +50C to +220C
 Cold Temp range :-75C to +70C
 Capacity : 300 litre
 (Approx. 25 kg of packages)

Device Reliability - Hot Carrier Injection (HCI)

Capabilities:
 - 15mA current per DUT
 - ± 10V stress voltage per DUT
 - Temperature - 30°C to 195°C
 - Total capacity of 96 DUTs
 - Possibility to test ± 100V at reduced capacity



Product Reliability - High Temperature Bake Oven

Capabilities :
 Temperature : 350C max
 With Nitrogen gas.



Device Reliability - Time-Dependent-Dielectric-Breakdown

Capabilities:
 - 2mA current per DUT
 - ± 25V or 0-50V stress voltage per DUT
 - Temperature 60° 250°C
 - Total capacity of 480 DUTs over 4 furnaces



High Temperature Operating Life (HTOL)

Capabilities:
 - 0.04mA to 300mA current per DUT
 - 5V compliance voltage per DUT
 - Temperature 60°C to 350°C

Temperature Cycle

Capabilities:
 Temp Range : - 80C to 125C
 (Operating)
 Ramp rate : 10C to 40C per minute



Product Reliability - Halt / Hass test

Capabilities :
 Highly Accelerated
 Stress Test
 Temp range :
 100C to +200C
 Vibration:
 Over 60Grms
 Temp change rate:
 Up to 60C per minute



Temperature Humidity Bias (THB)

Capabilities :
 Temp : -65C to 177C
 Huml : 5 to 98% RH
 Rate : 3 degC/min
 Capacity : 765 litre



HAST / PCT Test

Temp Range
 105 to 150 degC
 Humidity Range
 65% to 100% RH
 Pressure Range :
 1 to 3 atm
 Time Range :
 0.1 to 999 hrs



Product Reliability - Reflow Oven

Capabilities :
 4 Heating zone
 2 Cooling zone
 Temp (std) : Up to 420C
 Temp Accuracy : ± 2C
 Time Mode (Dwell & Travel) :
 7 sec to 99 min (per zone)



Product Reliability - AutoClave/PCT

Capabilities :
 - Temp: 105 to 162C
 - Humidity: 75% to 100%
 - Pressure: 0.2 ~ 4kg/cm2G



Capabilities:
 - 0.04mA to 300mA current per DUT
 - 5V compliance voltage per DUT
 - Temperature 60°C to 350°C
 - Total capacity of 768 DUTs over 4 furnaces

Device Reliability - Electromigration (EM)

